Title (en)
    Sacrificial substrate for use in wafer cutting

Title (de)
    Opfersubstrat zur Verwendung beim Schneiden von Wafern

Title (fr)
    Substrat sacrificielle à utiliser dans un découpage de tranche

Publication
    EP 2572850 A1 20130327 (EN)

Application
    EP 11190570 A 20111124

Priority
    • EP 11182589 A 20110923
    • EP 11190570 A 20111124

Abstract (en)
    The invention relates to a sacrificial substrate (1) having a mounting surface (2) for holding a piece of material (3), such as an ingot, brick or core, for cutting a plurality of wafers from the piece of material (3), wherein the sacrificial substrate (1) has an E-modulus smaller than 6000 MPa, more preferably smaller than 5000 MPa, most preferably smaller than 4000 MPa. The invention also relates to a method of making a plurality of wafers of a piece of material (3), such as an ingot, brick or core, comprising the steps of: mounting the piece of material (3) to a sacrificial substrate (1), preferably by gluing; mounting the sacrificial substrate (1) with the piece of material (3) in a cutting device; and cutting the piece of material (3) into a plurality of wafers.

IPC 8 full level
    B28D 5/00 (2006.01)

CPC (source: EP)
    B28D 5/0082 (2013.01)

Citation (applicant)
    • WO 2010128011 A1 20101111 - MEYER BURGER AG [CH], et al
    • EP 2111960 A1 20091028 - APPLIED MATERIALS SWITZERLAND [CH], et al

Citation (search report)
    • [XY] DE 2044482 A1 19720323
    • [XY] US 2009199836 A1 20090813 - GUPTA PUNEET [US]
    • [Y] WO 2009040109 A1 20090402 - SCHOTT AG [DE], et al
    • [A] US 2011162504 A1 20110707 - DOI YUHITO [JP], et al
    • [AD] EP 2111960 A1 20091028 - APPLIED MATERIALS SWITZERLAND [CH], et al

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    CN103522428A

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Designated extension state (EPC)
    BA ME

DOCDB simple family (publication)
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    WO 2013042055 A1 20130328

DOCDB simple family (application)
    EP 11190570 A 20111124; CN 201280057521 A 20120919; IB 2012054972 W 20120919; IN 3101DEN2014 A 20140418